Abstracts

Characterization of RF-IC Packages by Multiport Excitation

R.T. Kollipara, J. Williams and V.K. Tripathi. "Characterization of RF-IC Packages by Multiport Excitation." 1996 MTT-S International Microwave Symposium Digest 96.3 (1996 Vol. III [MWSYM]): 1727-1729.

A new measurement technique based on multiport TDR excitation is presented. The technique is quite accurate and is used to characterize low-cost and small lead frame plastic packages. The extracted self and mutual inductance and capacitance values of a typical package are presented.

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